

# LN2162C13TR

## Surface Mounting Chip LED

GW Bi-Color Type

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

#### • Red

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	45	mW
Forward current	$I_F$	15	mA
Pulse forward current *	$I_{FP}$	60	mA
Reverse voltage	$V_R$	3	V
Operating ambient temperature	$T_{opr}$	-25 to +80	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-30 to +85	$^\circ\text{C}$

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

### ■ Lighting Color / Lens Color

- Red / Clear
- Green / Clear

#### • Green

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	45	mW
Forward current	$I_F$	15	mA
Pulse forward current *	$I_{FP}$	60	mA
Reverse voltage	$V_R$	4	V
Operating ambient temperature	$T_{opr}$	-25 to +80	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-30 to +85	$^\circ\text{C}$

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

### ■ Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

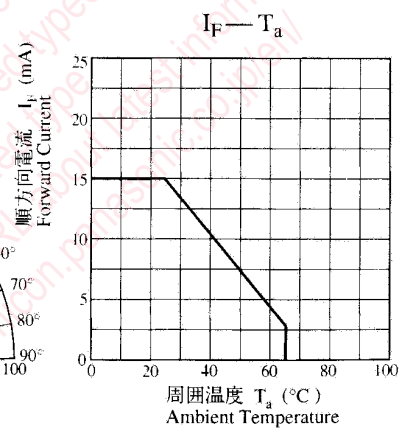
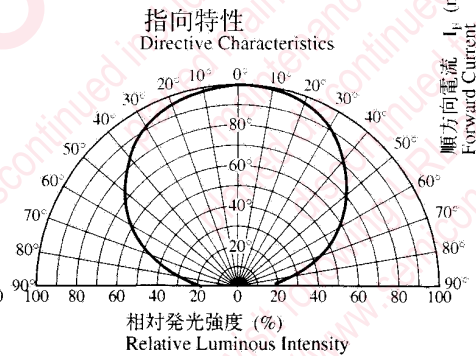
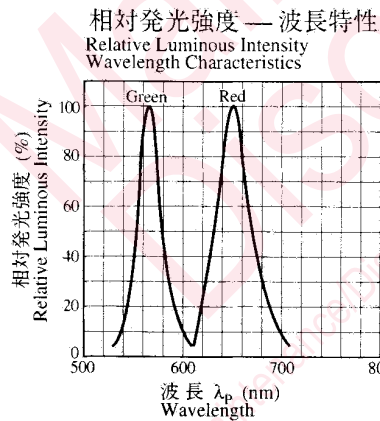
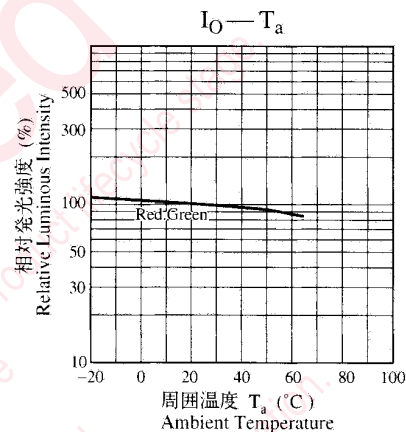
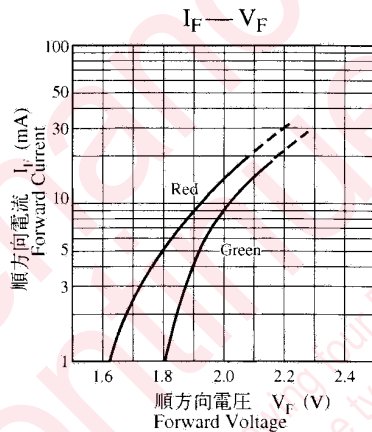
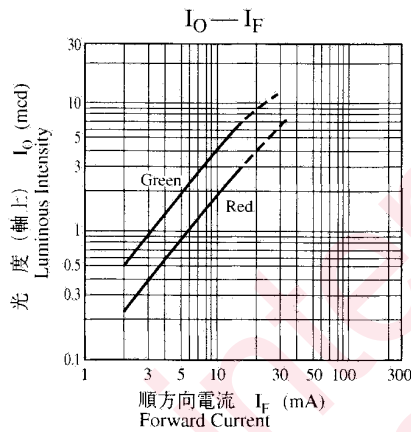
#### • Red

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$		0.65	1.8		mcd
Forward current	$I_F$			10		mA
Forward voltage	$V_F$	$I_F = 10\text{ mA}$		2.0	2.8	V
Peak emission wavelength	$\lambda_p$	$I_F = 10\text{ mA}$		650		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		40		nm
Reverse current	$I_R$	$V_R = 3\text{ V}$			10	$\mu\text{A}$

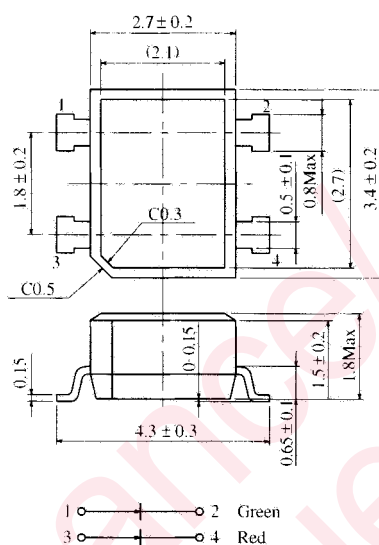
■ Electro-Optical Characteristics (Continued)  $T_a = 25^\circ\text{C}$

• Green

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$		1.5	4.0		mcd
Forward current	$I_F$			10		mA
Forward voltage	$V_F$	$I_F = 10\text{ mA}$		2.05	2.8	V
Peak emission wavelength	$\lambda_P$	$I_F = 10\text{ mA}$		565		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		30		nm
Reverse current	$I_R$	$V_R = 4\text{ V}$			10	$\mu\text{A}$



■ Package (Unit: mm)



• Pin name

- 1, 3: Anode
- 2, 4: Cathode

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